

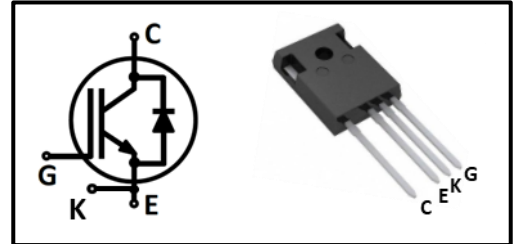
## Features

- Easy parallel switching capability due to positive temperature coefficient in  $V_{CEsat}$
- Low  $V_{CEsat}$ , fast switching
- High ruggedness, good thermal stability
- Very tight parameter distribution

## Applications

- UPS
- PFC
- PTC Heater
- Climate Compressor

Type	Marking	Package Code
AMPBZ50N65ED	AMP50N65ED	TO-247-4



## Maximum Rated Values <sup>1</sup>

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{CE}$	650	V
DC collector current <sup>2</sup>			A
$T_C=25^\circ\text{C}$	$I_C$	80	
$T_C=100^\circ\text{C}$		50	
Pulsed collector current <sup>3</sup>	$I_{Cpuls}$	200	
Diode forward current <sup>2</sup>			
$T_C=25^\circ\text{C}$	$I_F$	80	
$T_C=100^\circ\text{C}$		50	
Diode pulsed current <sup>3</sup>	$I_{Fpuls}$	200	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Transient Gate-emitter voltage ( $t_p \leq 10\mu\text{s}$ )		$\pm 30$	
Power dissipation			W
$T_C=25^\circ\text{C}$	$P_{tot}$	300	
$T_C=100^\circ\text{C}$		150	
Operating junction temperature	$T_j$	-55~175	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55~150	

1:Reference standard: JESD-022 2: limited by  $T_{jmax}$  3:  $T_p$  limited by  $T_{jmax}$  ;



**Thermal Characteristics**

Parameter	Symbol	Min	Typ	Max	Unit
IGBT thermal resistance, junction-case	$R_{thJC}$	-	-	0.5	K/W
Diode thermal resistance, junction-case	$R_{thJCD}$	-	-	0.65	
Thermal Resistance, junction-ambient	$R_{thJA}$	-	-	40	

**Electrical Characteristics (at  $T_j=25^\circ\text{C}$ , unless otherwise specified)**  
**Static Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=0.25mA$	650	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=50A, T_j=25^\circ\text{C}$	-	1.60	1.90	
		$T_j=125^\circ\text{C}$	-	1.90	-	
		$T_j=150^\circ\text{C}$	-	1.98	-	
Diode forward voltage	$V_F$	$V_{GE}=0V, I_F=50A, T_j=25^\circ\text{C}$	-	2.00	2.30	
		$T_j=125^\circ\text{C}$	-	1.81	-	
		$T_j=150^\circ\text{C}$	-	1.76	-	
G-E threshold voltage	$V_{GE(th)}$	$I_C=1mA, V_{CE}=V_{GE}$	4.5	5.5	6.5	
C-E leakage current	$I_{CES}$	$V_{CE}=650V, V_{GE}=0V, T_j=25^\circ\text{C}$	-	-	0.01	
		$T_j=150^\circ\text{C}$	-	-	1.0	
G-E leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$	-	-	250	nA
Transconductance	$g_{FS}$	$V_{CE}=20V, I_C=50A$	-	21	-	S

**Dynamic Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Input capacitance	$C_{iss}$	$V_{CE}=25V, V_{GE}=0V, f=1MHz$	-	5573	-	pF
Output capacitance	$C_{oss}$		-	148	-	
Reverse transfer capacitance	$C_{riss}$		-	80	-	
Gate charge	$Q_G$	$V_{CC}=300V, I_C=50A, V_{GE}=15V$	-	230	-	nC



### IGBT Switching Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit	
Turn-on delay time	$t_{d(on)}$	$T_j=25^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	107	-	ns	
Rise time	$t_r$		-	62	-		
Turn-off delay time	$t_{d(off)}$		-	265	-		
Fall time	$t_f$		$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	48	-	mJ
Turn-on energy	$E_{on}$			-	0.90	-	
Turn-off energy	$E_{off}$			-	1.12	-	
Total switching energy	$E_{ts}$			-	2.02	-	
Turn-on delay time	$t_{d(on)}$	$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	100	-	ns	
Rise time	$t_r$		-	62	-		
Turn-off delay time	$t_{d(off)}$		-	335	-		
Fall time	$t_f$		$T_j=150^{\circ}\text{C}$ , $V_{CC}=400\text{V}$ , $I_C=50\text{A}$ , $V_{GE}=0/15\text{V}$ , $R_G=10\Omega$ , Inductive load	-	50	-	mJ
Turn-on energy	$E_{on}$			-	1.45	-	
Turn-off energy	$E_{off}$			-	1.35	-	
Total switching energy	$E_{ts}$			-	2.80	-	

### Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode reverse recovery time	$t_{rr}$	$T_j=25^{\circ}\text{C}$ , $V_R=400\text{V}$ , $I_F=50\text{A}$ , $di_F/dt=640\text{A}/\mu\text{s}$	-	57	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	0.39	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	10.6	-	A
Diode reverse recovery time	$t_{rr}$	$T_j=150^{\circ}\text{C}$ , $V_R=400\text{V}$ , $I_F=50\text{A}$ , $di_F/dt=640\text{A}/\mu\text{s}$	-	92.8	-	ns
Diode reverse recovery charge	$Q_{rr}$		-	1.48	-	$\mu\text{C}$
Diode peak reverse recovery current	$I_{rrm}$		-	24	-	A

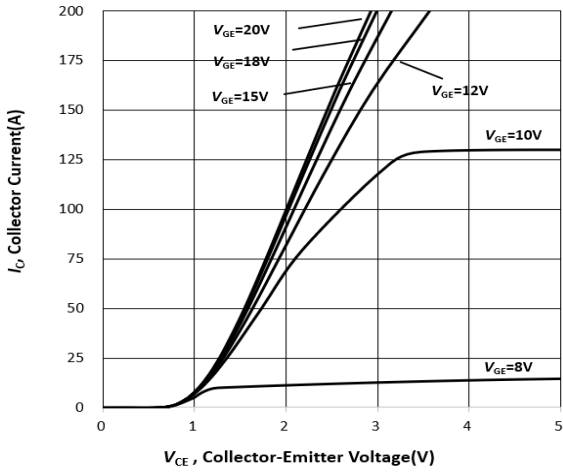


Figure 1. Typical output characteristic ( $T_j = 25^\circ\text{C}$ )

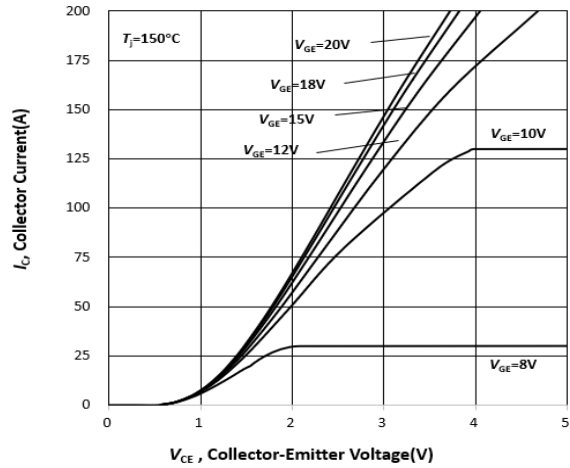


Figure 2. Typical output characteristic ( $T_j = 150^\circ\text{C}$ )

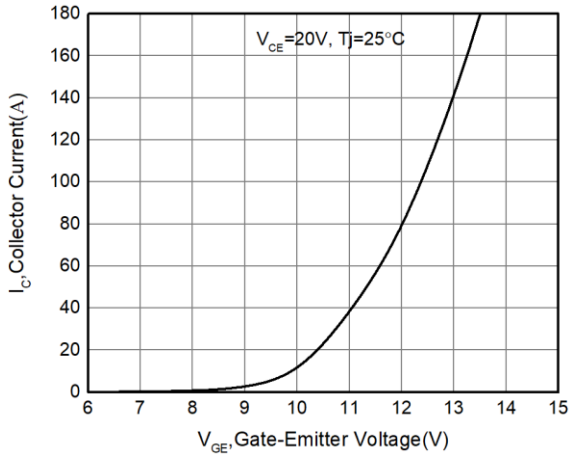


Figure 3. Typical transfer characteristic ( $T_j = 25^\circ\text{C}$ )

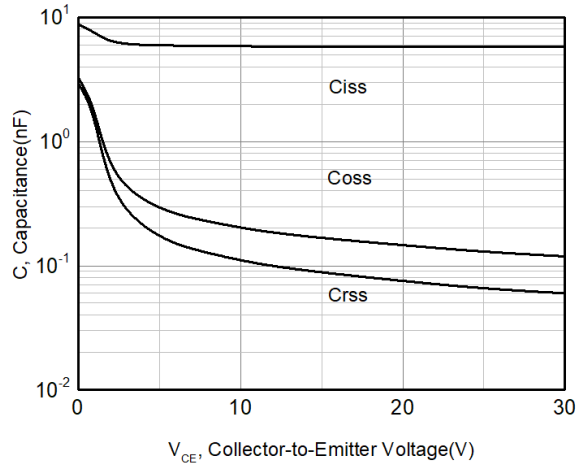


Figure 4. Capacitance characteristic ( $V_{GE} = 0\text{V}$ ,  $f = 1\text{MHz}$ )

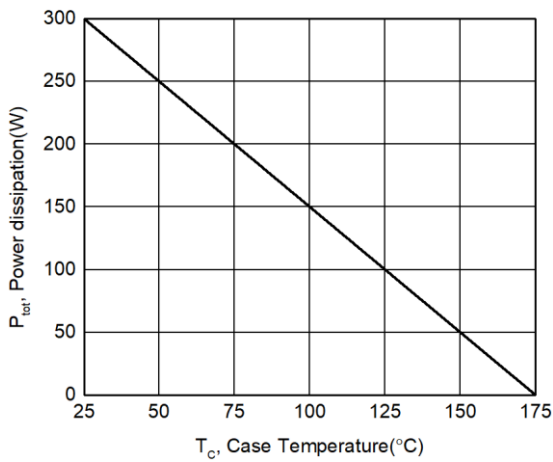


Figure 5. Power dissipation as a function of case temperature ( $T_j \leq 175^\circ\text{C}$ )

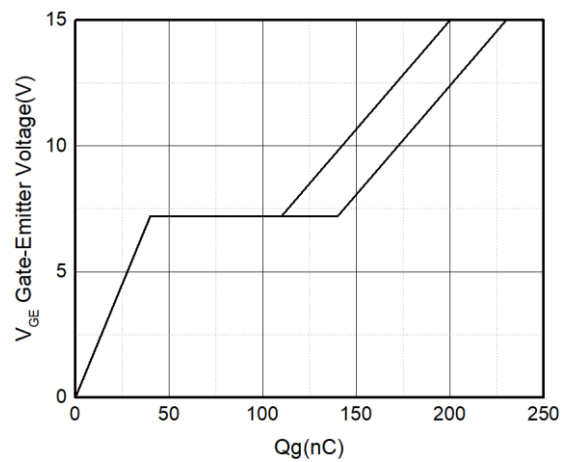


Figure 6. Typical gate charge ( $I_C = 50\text{A}$ )

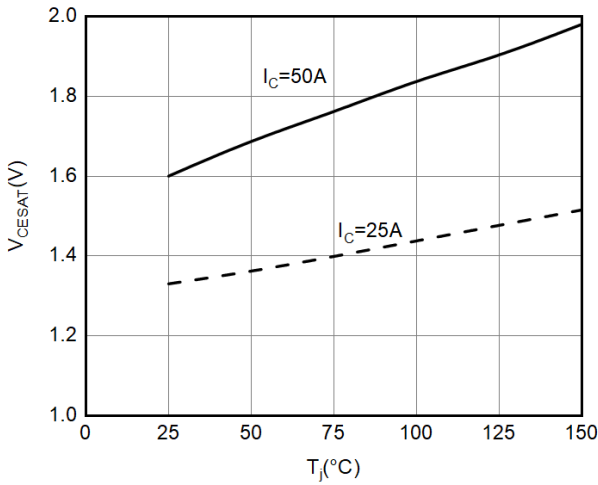


Figure 7.  $V_{CESAT}$  as a function of junction temperature ( $V_{GE}=15V$ )

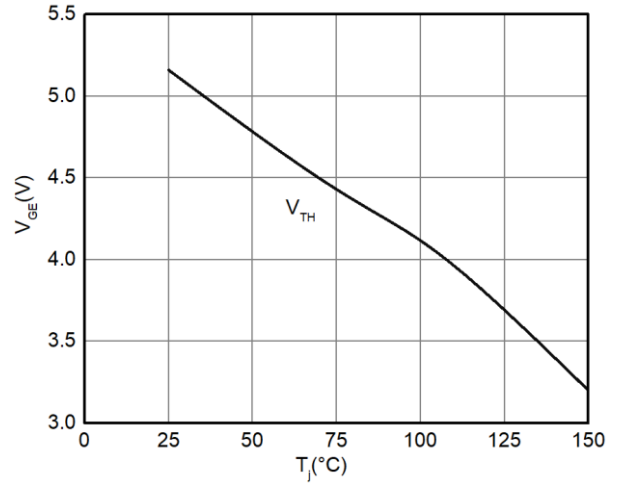


Figure 8.  $V_{TH}$  as a function of junction temperature ( $I_{CE}=250\mu A$ )

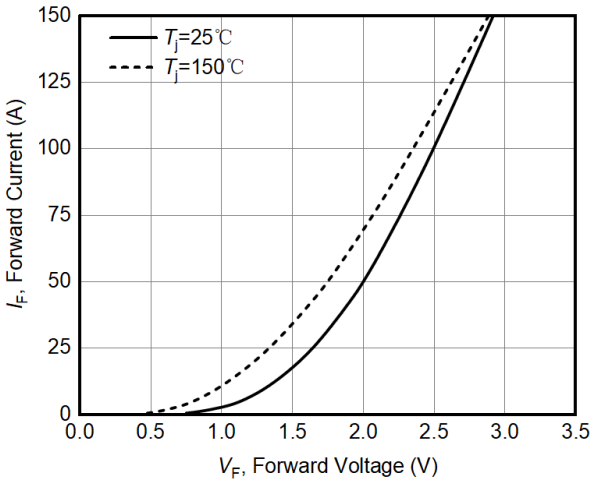


Figure 9. Typical diode forward current as a function of forward voltage

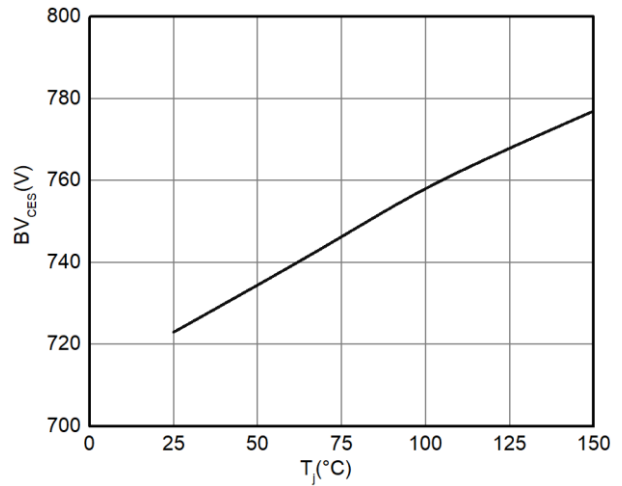


Figure 10.  $BV$  as a function of junction temperature ( $I_{CE}=250\mu A$ )

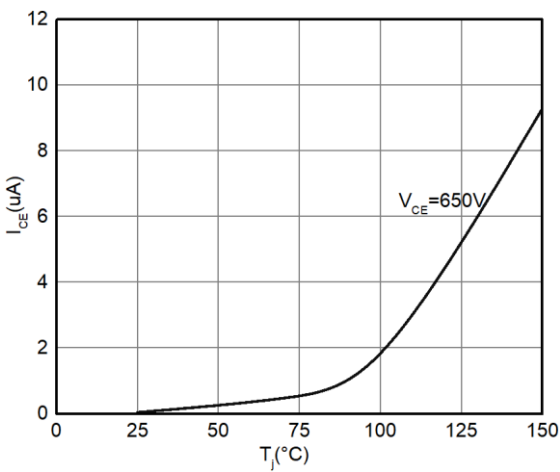


Figure 11.  $I_{CES}$  leakage current as a function of junction temperature

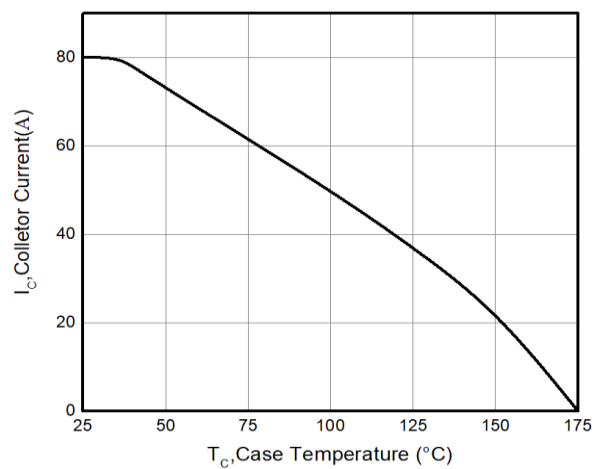


Figure 12. Collector current as a function of case temperature ( $V_{GE}\geq 15V$ ,  $T_j\leq 175^\circ C$ )

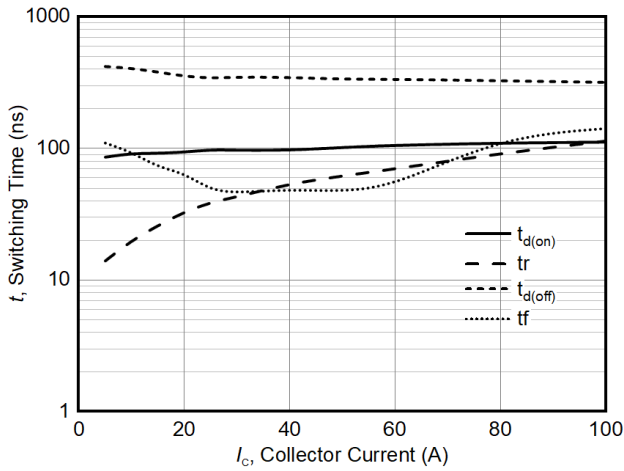


Figure 13. Typical switching times as a function of collector current  
( $T_j=150\text{ }^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $R_{G(on)}=R_{G(off)}=10\Omega$ )

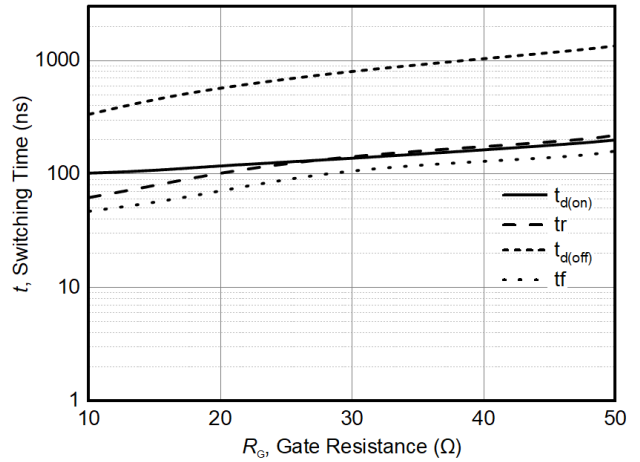


Figure 14. Typical switching times as a function of gate resistance  
( $T_j=150\text{ }^\circ\text{C}$ ,  $V_{CE}=400\text{V}$ ,  $I_C=50\text{A}$ )

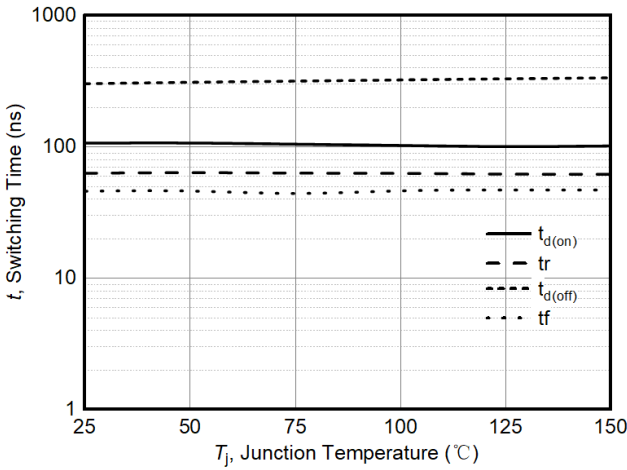


Figure 15. Typical switching times as a function of junction temperature  
( $V_{CE}=400\text{V}$ ,  $I_C=50\text{A}$ ,  $R_{G(on)}=R_{G(off)}=10\Omega$ )

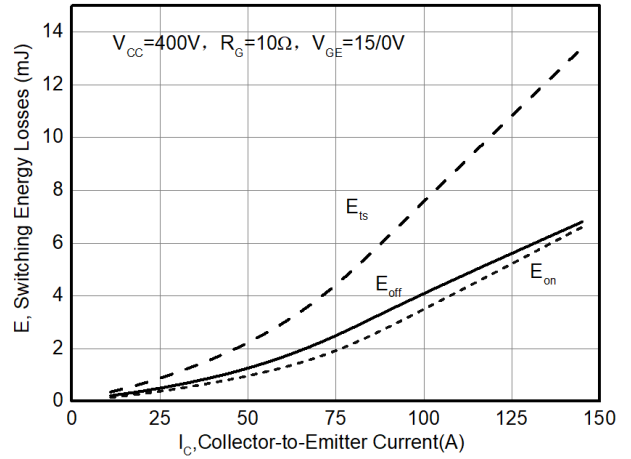


Figure 16.  $E_{on}$ ,  $E_{off}$  as a function of  $I_C$   
( $T_j=25\text{ }^\circ\text{C}$ )

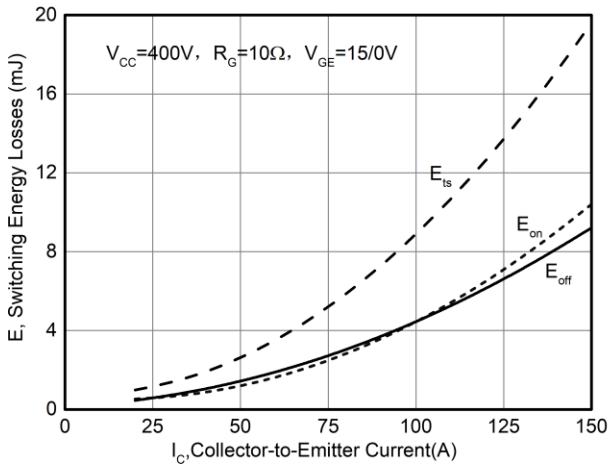


Figure 17.  $E_{on}$ ,  $E_{off}$  as a function of  $I_C$   
( $T_j=150\text{ }^\circ\text{C}$ )

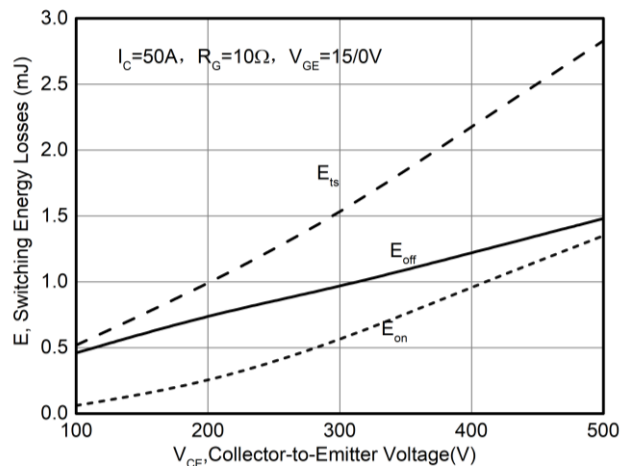


Figure 18.  $E_{on}$ ,  $E_{off}$  as a function of  $V_{CE}$   
( $T_j=25\text{ }^\circ\text{C}$ )

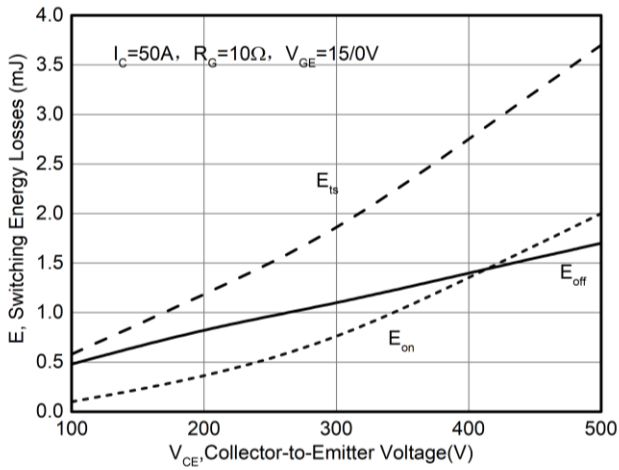


Figure 19.  $E_{on}$ ,  $E_{off}$  as a function of  $V_{CE}$  ( $T_j=150^\circ C$ )

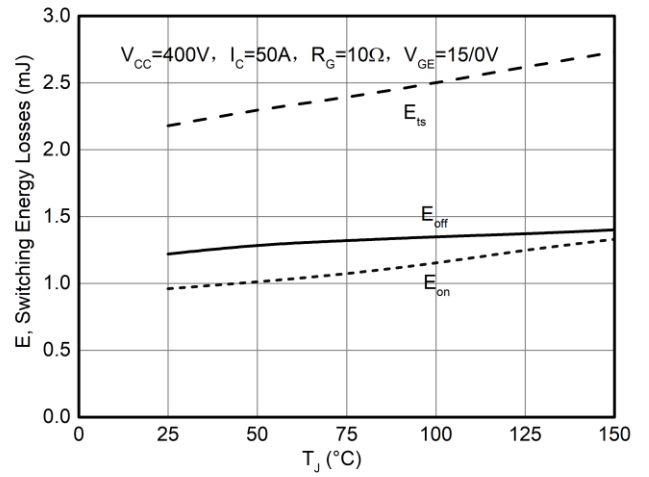


Figure 20.  $E_{on}$ ,  $E_{off}$  as a function of  $T_j$

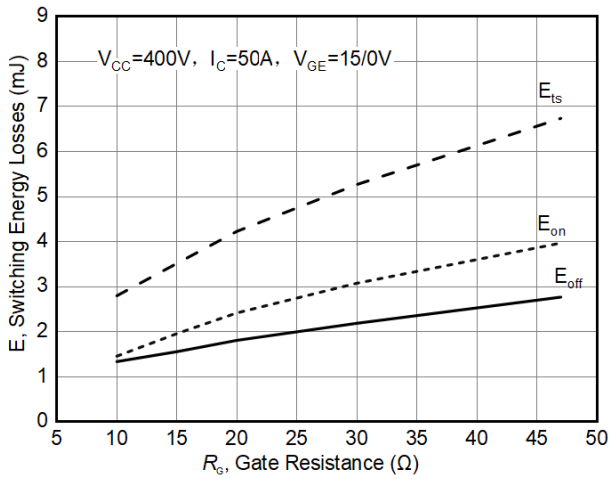


Figure 21.  $E_{on}$ ,  $E_{off}$  as a function of gate resistance ( $T_j=150^\circ C$ )

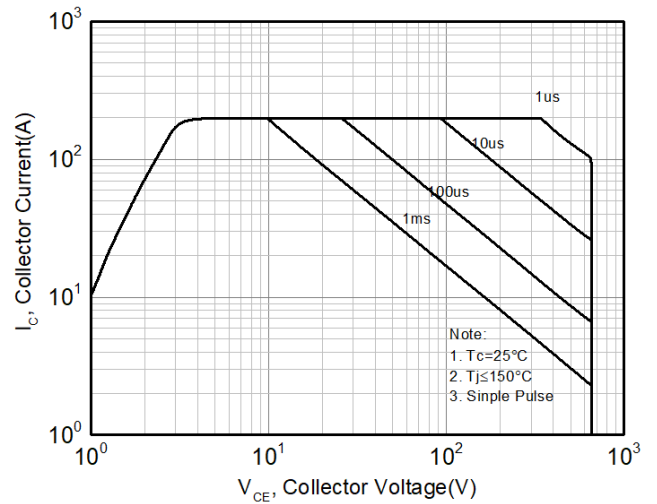
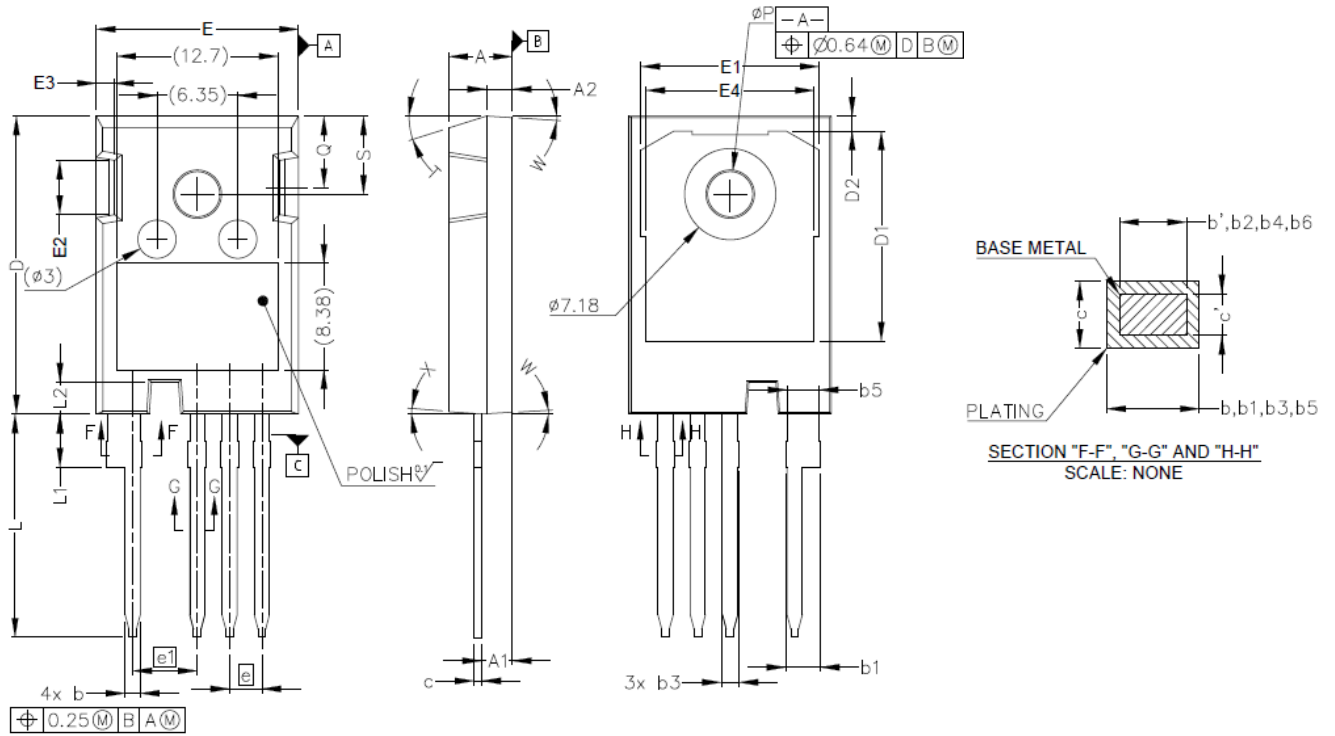


Figure 22. FBSOA

TO-247-4



SYMBOL	MILLIMETERS		SYMBOL	MILLIMETERS	
	MIN	MAX		MIN	MAX
A	4.83	5.21	E1	13.10	14.15
A1	2.29	2.54	E2	3.68	5.10
A2	1.91	2.16	E3	1.00	1.90
b'	1.07	1.28	E4	12.38	13.43
b	1.07	1.33	e	2.54 BSC	
b1	2.39	2.94	e1	5.08 BSC	
b2	2.39	2.84	N	4	
b3	1.07	1.60	L	17.31	17.82
b4	1.07	1.50	L1	3.97	4.37
b5	2.39	2.69	L2	2.35	2.65
b6	2.39	2.64	$\phi P$	3.51	3.65
c'	0.55	0.65	Q	5.49	6.00
c	0.55	0.68	S	6.04	6.30
D	23.30	23.60	T	17.5° REF.	
D1	16.25	17.65	W	3.5° REF.	
D2	0.95	1.25	X	4° REF.	
E	15.75	16.13			





**Revision History:**

Revision	Date	Subjects (major changes since last revision)
1.0	2023-02	Initial Version



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